

Symbol	Characteristic / Test Conditions	Min	Typ	Max	Unit
$R_{\theta JC}$	Junction-to-Case Thermal Resistance			2.0	$^{\circ}\text{C}/\text{W}$
$W_T$	Package Weight		0.07		oz
			1.9		g
Torque	Maximum Mounting Torque			6.4	lb-in
				0.7	N-m

Microsemi reserves the right to change, without notice, the specifications and information contained herein.

# TYPICAL PERFORMANCE CURVES

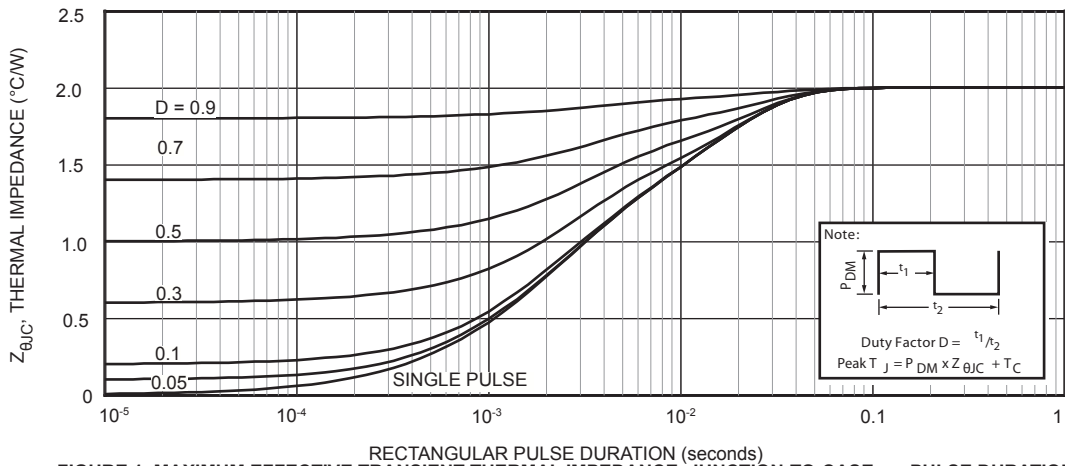


FIGURE 1. MAXIMUM EFFECTIVE TRANSIENT THERMAL IMPEDANCE, JUNCTION-TO-CASE vs. PULSE DURATION

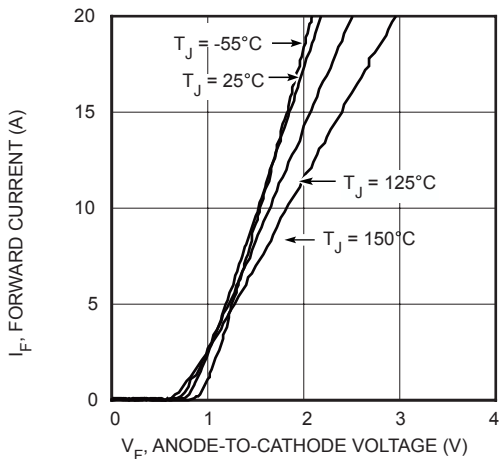


FIGURE 2. Forward Current vs. Forward Voltage

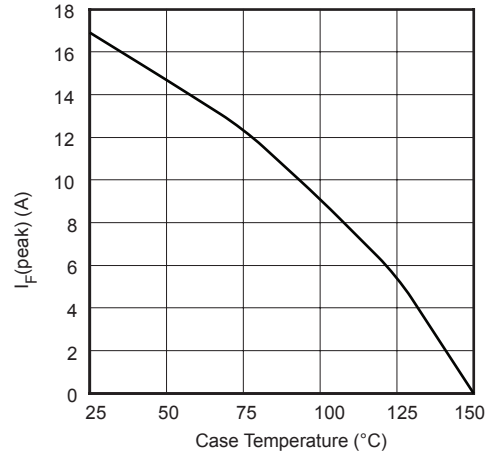


FIGURE 3. Maximum Forward Current vs. Case Temperature

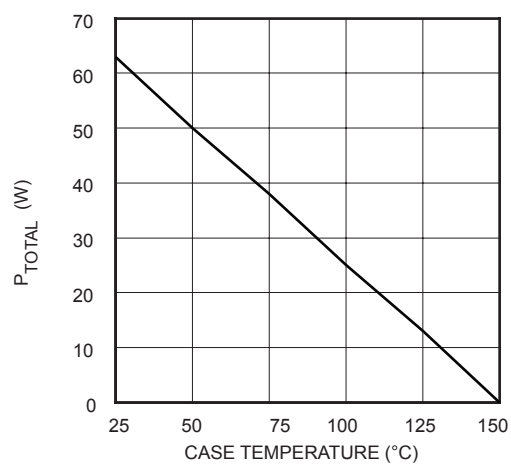


Figure 4. Maximum Power Dissipation vs. Case Temperature

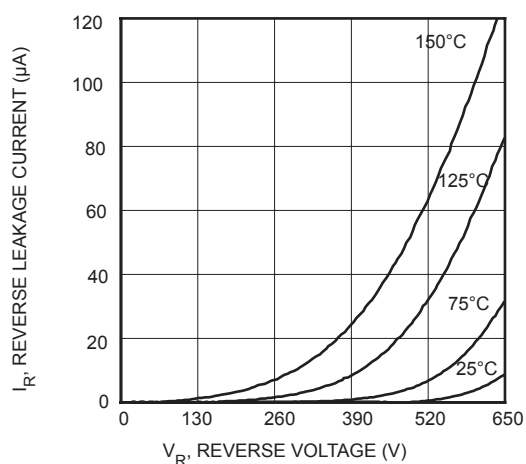


Figure 5. Reverse Leakage Currents vs. Reverse Voltage

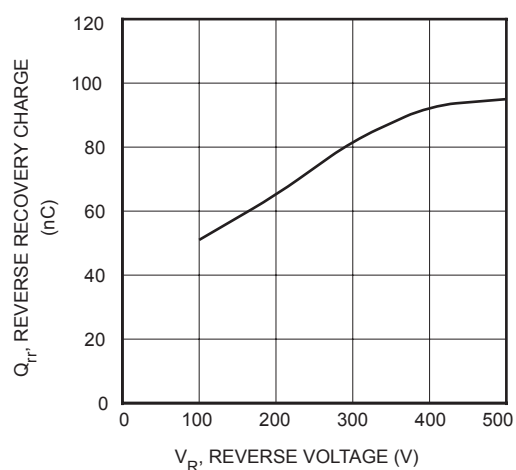
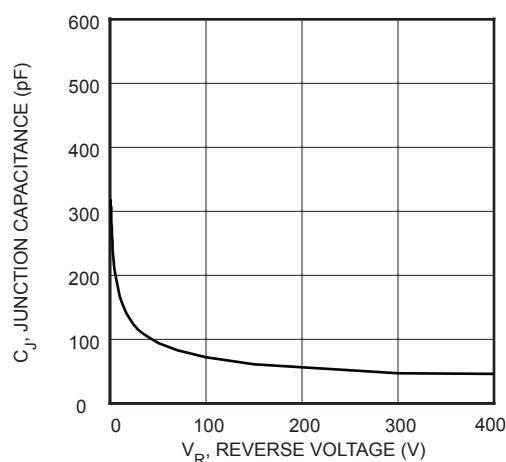
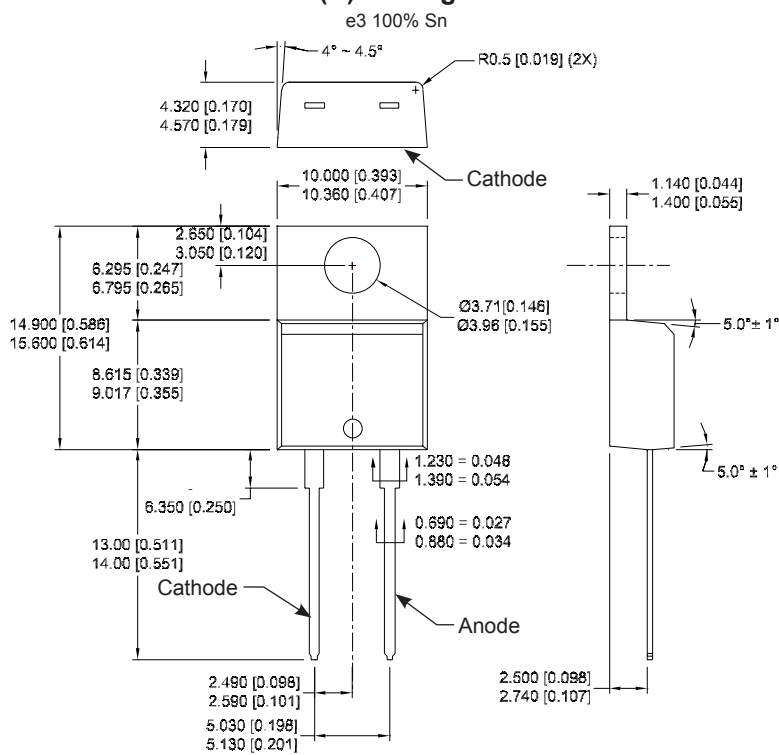
Figure 6. Reverse Recovery Charge vs. V<sub>R</sub>

Figure 7. Junction Capacitance vs. Reverse Voltage

## TO-220 (K) Package Outline



Dimensions in millimeters and [inches]

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